



Accelerating the next technology revolution

# IEUVI Optics Contamination / Lifetime TWG Meeting

October 2, 2008 – Lake Tahoe, CA, US

Chair: A. Wüest, SEMATECH

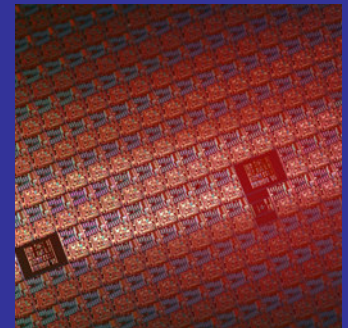
Co-chairs:

Asia/Pacific: Y. Fukuda, Canon

Europe: R. Verberk, TNO

US: T. Lucatoro, NIST

K. Orvek, Intel/SEMATECH



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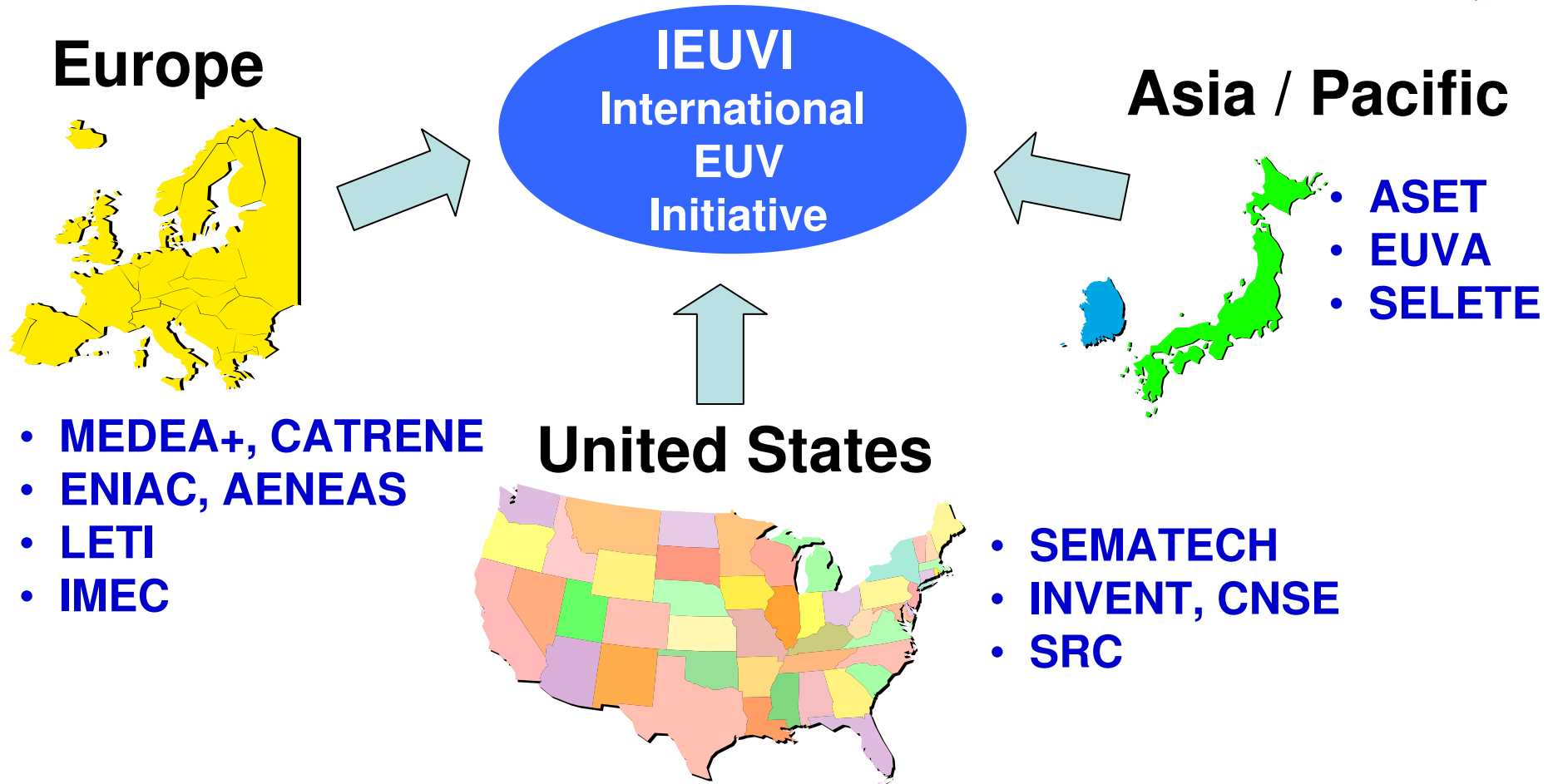
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# International EUV Initiative (IEUVI)



**IEUVI Mission: To further the coordination of collaborative efforts among leading EUVL R&D consortia.**

**<http://www.ieuvi.org>**

# IEUVI Organization



## IEUVI Board

<b>Chair:</b>	<b>Paolo Gargini</b>	<b>Intel</b>		
<b>Member Organizations:</b>	<b>CEA / LETI</b>	<b>(EU)</b>	<b>Selete</b>	<b>(JP)</b>
	<b>IMEC</b>	<b>(EU)</b>	<b>EUVA</b>	<b>(JP)</b>
	<b>MEDEA+, CATRENE, ENIAC, AENEAS</b>	<b>(EU)</b>	<b>SEMATECH</b>	<b>(US)</b>

## IEUVI Technical Working Groups (TWG)

### Optics Contamination TWG

<b>Chair:</b>	<b>Andrea Wüest</b>	<b>(US)</b>	<b>SEMATECH</b>
<b>Co-Chairs:</b>	<b>Yasuaki Fukuda</b>	<b>(JP)</b>	<b>EUVA / Canon</b>
	<b>Rogier Verberk</b>	<b>(EU)</b>	<b>TNO</b>
	<b>Tom Lucatorto</b>	<b>(US)</b>	<b>NIST</b>

### Resist TWG

<b>Chair:</b>	<b>Serge Tedesco</b>	<b>(EU)</b>	<b>CEA / LETI</b>
<b>Co-Chair</b>	<b>Jacque Georger</b>	<b>(US)</b>	<b>SEMATECH / Intel</b>
	<b>TBD</b>	<b>(AP)</b>	

### Mask TWG

<b>Chair:</b>	<b>Kevin Orvek</b>	<b>(US)</b>	<b>SEMATECH / Intel</b>
<b>Co-Chairs:</b>	<b>Iwao Nishiyama</b>	<b>(JP)</b>	<b>Selete / NECEL</b>
	<b>Jinho Ahn</b>	<b>(KR)</b>	<b>Hanyang Univ.</b>
	<b>Jan Hendrik Peters</b>	<b>(EU)</b>	<b>AMTC</b>

### Source TWG

<b>Chair:</b>	<b>Frank Goodwin</b>	<b>(US)</b>	<b>SEMATECH</b>
<b>Co-Chair:</b>	<b>Masashi Ogawa</b>	<b>(JP)</b>	<b>EUVA</b>
	<b>TBD</b>	<b>(EU)</b>	

# Agenda

Lake Tahoe, CA, USA - October 2, 2008



7:45`	<b>Breakfast</b>	
8:00	<b>Welcome and Introductions</b>	A. Wüest, SEMATECH
8:15	<b>Survey Results</b>	A. Wüest, SEMATECH
	<b>Exposure Tool Update on Contamination Issues</b>	
8:30	• SFET Optics Contamination Learning Update	Iwao Nishiyama, Selete
8:45	• Intel MET Cold Trap results and Related Data	Roman Caudillo, Intel
9:00	• NIST Tools to Characterize Resist Outgas and Analyze Stepper Contaminants	Thomas Lucatorto, NIST
9:15	• Contamination and Cleaning of MET Illumination Mirrors	Erik Sohmen, Carl Zeiss SMT
9:30	• EUV Mask Contamination During Use	Ted Liang, Intel
9:45	• Discussion	
10:00	<b>Break</b>	
	<b>Resist Outgassing Contribution</b>	
10:20	• Collector Upgrade for Higher Power Optics Contamination Testing	Gregory Denbeaux, CNSE
10:35	• EUV Resist Outgassing Activity at Selete	Toshiro Itani, Selete
10:50	• SEMATECH Policy on EUV Resist Outgassing	Kevin Orvek, Intel/SEMATECH
11:05	• Photoresist Outgassing for EUV HVM Exposure Tool by Canon and Nikon	Takashi Aoki, Nikon
11:20	• Resist Outgas Metrology Update	Noreen Harned, ASML
11:35	• Discussion	
12:00	<b>Adjourn</b>	

# Next IEUVI Optics Contamination and Lifetime TWG Meeting



- SPIE Advanced Lithography, San Jose, CA, USA
- February 26, 2009
- Presentations will be available on [www.ieuvi.org](http://www.ieuvi.org)

# Thank you



Thank you very much for your participation and contribution!